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John Lau , Heng-Chieh Chien and high cooling ability and very low pressure drop 3D IC integration  
This system consists of a silicon interposer with through

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3D integration includes such technologies as 3D WLP; Through silicon vias (TSVs) are holes created in a silicon wafer using an etch process.

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TSV Through Silicon Via Technology for 3D-integration Solience Ngansso Prof. Dr. Peter Fischer  
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The through silicon via (TSV) High aspect ratio copper through-silicon-vias for 3D integration. Microelectron. Eng., 85 (10) (Oct. 2008), pp. 1952 1956.

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Understanding Heterogeneous 3D Integration; Who Invented the Through Silicon Via (TSV) but thanks really go to John Lau who shared this article with 3D InCites!

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